

CLAIMS

What is claimed is:

1. An electronics component mounting system, comprising:
a first mounting structure including:
5 two generally parallel and opposing spacers;
a plurality of supports extending from the spacers, the supports being
configured to engage holes defined on a surface of a first electronics
component to be mounted on the first mounting structure,
a base portion extending between the two generally parallel and
10 opposing spacers, the spacers and the supports being generally orthogonal to
the base portion.
2. The system of claim 1, wherein each spacer defines an orifice configured to
allow a fastening mechanism to pass therethrough and engage thereto.
3. The system of claim 1, further comprising a fastening mechanism to secure
15 the first mounting structure to the first electronics component.
4. The system of claim 3, wherein the fastening mechanism comprises a hook
and loop material.
5. The system of claim 1, wherein the supports are tapered so that the supports
decrease in size as the supports extend away from the spacers.

6. The system of claim 5, wherein the supports are made of a material that is harder than the material of the holes defined on the surface of the first electronics component.

7. The system of claim 1, further comprising:
5 an electronics base, the first mounting structure being rigidly attached to the electronics base, the first mounting structure and the electronics base being separately formed.

8. The system of claim 1, further comprising:
an electronics base, the first mounting structure being integrally formed
10 from the electronics base.

9. The system of claim 1, wherein the base portion extending between the spacers includes a plurality of sharp points configured to face and be secured to a surface of a second electronics component onto which the first mounting structure and the first electronics component are stacked.

15 10. The system of claim 9, further comprising angled legs extending from the spacers and opposing the sharp points, the angled legs having an angled surface to engage the second electronics component.

11. The system of claim 9, further comprising:

a second mounting structure including:

two generally parallel and opposing second spacers;

a plurality of second supports extending from the second spacers, the

5 second supports being configured to engage holes defined on a surface of
the second electronics component to be mounted on the second mounting
structure,

10 a second base portion extending between the two generally parallel
and opposing second spacers, the second spacers and the second supports
being generally orthogonal to the second base portion.

12. The system of claim 1, further comprising:

a second mounting structure including:

two generally parallel and opposing second spacers;

a plurality of second supports extending from the second spacers, the

15 second supports being configured to engage holes defined on a surface of a
second electronics component to be mounted on the second mounting
structure,

20 a second base portion extending between the two generally parallel
and opposing second spacers, the second spacers and the second supports
being generally orthogonal to the second base portion, the second mounting
structure being configured to be mounted to the first electronics component.

13. An electronics component mounting apparatus, comprising:
component mounting means for securing a first electronics component to an
electronics base, including:

means for spacing the first electronics component from the
5 electronics base, and
means for engaging a plurality of holes defined on a surface of the
first electronics component to be mounted on the mounting mechanism, said
means for engaging extends from said means for spacing; and
means for securing the component mounting means to the first electronics
10 component.

14. The apparatus of claim 13, wherein said means for spacing defines a means
for allowing a fastening mechanism to engage thereto.

15. The apparatus of claim 13, wherein said means for engaging includes means
for engaging holes defined on the surface of the first electronics component to be
15 mounted on said component mounting means.

16. The apparatus of claim 13, further comprising means for biting into a
surface of a second electronics component onto which the component mounting means
and the first electronics component are stacked.

17. A method, comprising the steps of:
positioning a first electronics component onto opposing spacers of a first
mounting structure;
engaging a plurality of supports extending from the spacers with holes
5 defined on a surface of the first electronics component; and
securing the first electronics component and the first mounting structure to
each other.

18. The method of claim 17, wherein the step of securing includes the step of
engaging a fastening mechanism to orifices defined in the opposing spacers of the first
10 mounting structure.

19. The method of claim 17, wherein the step of engaging includes the step of
engaging the spacers with holes defined on the surface of the first electronics component.

20. The method of claim 17, further comprising the steps of:
securing a plurality of sharp points of a member connecting the opposing
15 spacers to a surface of a second electronics component onto which the first mounting
structure and the first electronics component are to be stacked.

21. The method of claim 20, further comprising the step of resting angled legs
extending from the opposing spacers and opposite the sharp points onto the second
electronics component.

22. The method of claim 20, further comprising the steps of
positioning the second electronics component onto opposing spacers of a
second mounting structure;

engaging a plurality of second supports extending from the second spacers
5 of the second mounting structure with second holes defined on a second surface of the
second electronics component, wherein the step of securing includes securing the second
electronics component to the first electronics component and the first mounting structure.